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said platform when supporting a wafer thereon leaves substantially no gap between said slanted surface and an outer periphery of the wafer;

positioning a wafer on said wafer lifter supported by said platform on said top portion of the at least four support fingers; and

lifting said wafer lifter to a position over said wafer pedestal and depositing said wafer onto said pedestal.

11. A method for self-centering a wafer on a wafer pedestal according to claim 10 further comprising the step, after said lifting step, of lowering said wafer lifter to deposit said wafer onto said wafer pedestal.

12. A method for self-centering a wafer on a wafer pedestal according to claim 10 further comprising the step of sputter depositing a metal layer on a top surface of said wafer.

13. A method for self-centering a wafer on a wafer pedestal according to claim 10 further comprising the step of self-centering the wafer on said wafer lifter during said positioning step when said wafer is guided into a center position by said slanted surface on said tip portion of the at least four support fingers.

14. A method for self-centering a wafer on a wafer pedestal according to claim 10 further comprising the step of providing four support fingers that are vertically mounted on said lifter body.

15. A method for self-centering a wafer on a wafer pedestal according to claim 10 further comprising the step of fabricating said lifter body with a material that has a rigidity of at least that of aluminum.

16. A method for self-centering a wafer on a wafer pedestal according to claim 10 further comprising the step of fabricating said lifter body with aluminum or stainless steel.